

One-Dimensional Constrained Blister Test to Measure Thin Film Adhesion

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A rectangular film is clamped at the opposite ends before being inflated into a blister by an external pressure, p . The bulging film adheres to a constraining plate with distance, w_0 , above. Increasing pressure expands the contact area of length, $2c$. Depressurization shrinks the contact area and ultimate detaches the film. The relation of (p, w_0, c) is established for a fixed interfacial adhesion energy. [DOI: 10.1115/1.4039171]

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Thin film adhesion is crucial in determining the reliability and lifespan of nano/micro-electronics parts and devices. We recently revisited the classical constrained blister test where a freestanding circular membrane clamped at the edge is pressurized to make adhesion contact with a constraining plate [1]. The relation between the measurable quantities of deformed film geometry, applied pressure, and contact radius, the materials parameters of interfacial adhesion energy and elastic modulus, and the spontaneous pull-off at critical pressure, are established based on a thermodynamic energy balance. In this paper, we extend the theoretical model to a rectangular film, and briefly compare the behavior of one-dimensional (1D) to two-dimensional (2D) geometry. Interested readers should refer to the earlier paper for engineering applications.

Figure 1 shows a linear elastic, rectangular film with unit width, length, $2a$, thickness, h , elastic modulus, E , Poisson's ratio, ν , and negligible flexible rigidity is clamped at its two opposite edges. External pressure, p , pushes the film into adhesion contact with a planar constraining plate a distance, w_0 , above, and a force per unit width, F , is necessary to hold the plate in equilibrium. The deformed film profile, $w(x)$, has a contact length, $2c$, and angle, θ , at the contact edge. Within the contact area, $w(x \leq c) = w_0$. In the freestanding sections ($c < |x| \leq a$), the film inclines at an angle $\psi \approx \partial w / \partial x$ and $\psi(x = c) = \theta$. For simplicity, all physical quantities (bold) are made dimensionless (plain) based on

$$\begin{aligned} w &= \frac{w}{h}, \quad w_0 = \frac{w_0}{h}, \quad c = \frac{c}{a}, \quad x = \frac{x}{a} \\ \gamma &= \gamma \left[\frac{6(1-\nu^2)a^4}{Eh^5} \right], \quad F = F \left[\frac{3(1-\nu^2)a^3}{Eh^4} \right], \\ p &= p \left[\frac{6(1-\nu^2)a^4}{Eh^4} \right], \quad G = G \left[\frac{6(1-\nu^2)a^4}{Eh^5} \right], \\ \sigma &= \sigma \left[\frac{12(1-\nu^2)a^2}{Eh^2} \right], \quad \psi = \frac{dw}{dx} = \left(\frac{a}{h} \right) \frac{dw}{dx} = \frac{a}{h} \times \psi \end{aligned}$$

Balance of vertical forces requires $2x.p - F = 2\sigma h \sin \psi \approx 2\sigma h \psi$ for small ψ , or, equivalently, $\psi = (2p/\sigma)(x - 1/\Phi)$ with $\Phi = p/F$ and $\Phi(\theta = 0) = 1/c$. Integration yields

$$w(x) = \int_x^1 \psi \cdot dr = w_0 \times \left[\frac{2(1-x) - (1-x^2)\Phi}{2(1-c) - (1-c^2)\Phi} \right] \quad (1)$$

The elastic strain, ϵ , is uniform in the overhanging sections ($c < |x| \leq 1$). Simple energy consideration yields the mechanical response given by

$$p = 8w_0^3 \times \left\{ \frac{(1+c+c^2)\Phi^3 - 3(1+c)\Phi^2 + 3\Phi}{(1-c)^3[(c+1)\Phi - 2]^3} \right\} \quad (2)$$

Equation (2) is valid during the loading stage when pressure increases. Thermodynamic energy balance yields the strain energy release rate given by [2]

$$G = \sigma h \left(\frac{\theta^2}{2} \right) + \frac{Eh}{2(1-\nu^2)} (\epsilon - \epsilon_0)^2 \quad (3)$$

with ϵ and ϵ_0 the membrane strain in the freestanding section and contact area, respectively. No delamination is expected for $G < \gamma$. As p exceeds a critical threshold, G reaches the adhesion energy with $G = \gamma$, and the film delaminates from the plate. Substituting Eq. (2) into Eq. (3)

$$\gamma = f_1 p^{4/3} + 3(f_2 p^{2/3} - \epsilon_0)^2 \quad (4)$$

where the functions are defined as

$$\begin{aligned} f_1(c, \Phi) &= \frac{(c\Phi - 1)^2}{2 \{ (1+c+c^2)\Phi^6 - 3(1+c)\Phi^5 + 3\Phi^4 \}^{1/3}} \\ f_2(c, \Phi) &= \frac{\{ (1+c+c^2)\Phi^2 - 3(1+c)\Phi + 3 \}^{1/3}}{6\Phi^{2/3}} \end{aligned}$$

To illustrate the model, Fig. 2 shows the special cases of $\gamma = 5$ and $\gamma = 20$ for a gap of $w_0 = 1$. Figure 3 shows the corresponding deformed profile. Along path OA, initial pressurization causes the film to bulge but yet to make contact with the plate ($c = 0$ and $\Phi \rightarrow \infty$) and $p = 8w_0^3$ from Eq. (2), where the blister height $w_0(p)$ is a monotonic increasing function. At A, $p = 8$ and the film touches the plate with a line contact. Increase in p along AB expands the contact area and raises F with $F = p c$, though θ

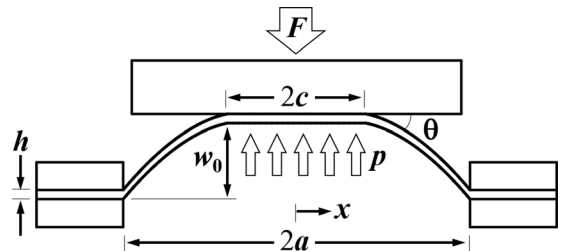


Fig. 1 Schematic of a pressurized 1D rectangular film adhering to a rigid constraining plate above

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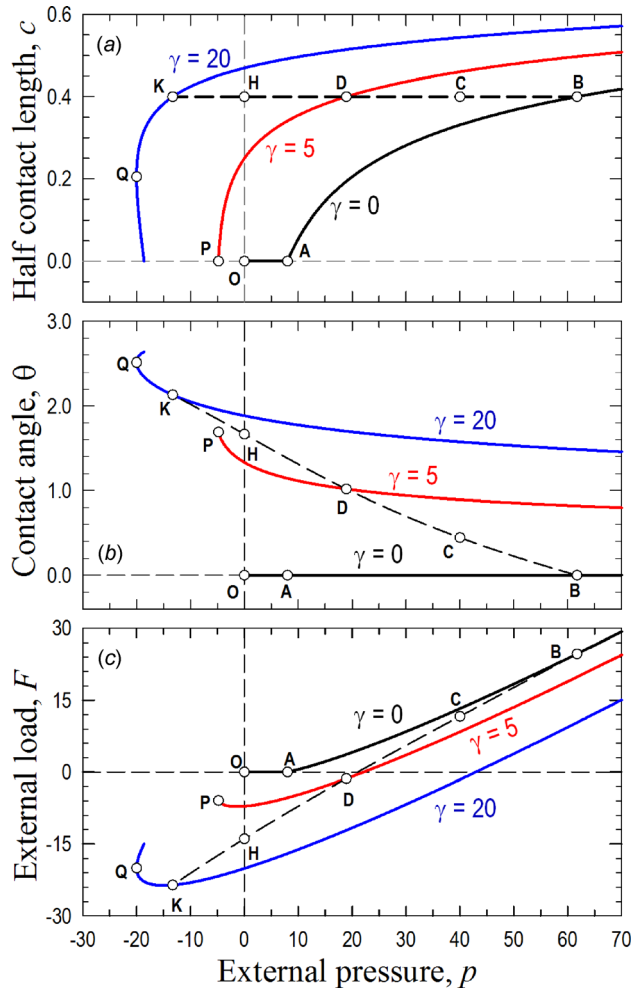


Fig. 2 Mechanical response of (a) contact length, c , (b) contact angle, θ , and (c) force to keep plate in equilibrium, F , as functions of applied pressure for $w_0 = 1$ and fixed adhesion energy. Initial loading along OA causes the film to bulge but yet to touch the plate. For $\gamma = 5$, pressurization along AB causes (a) contact to expand from null to maximum, (b) θ to remain at zero, and (c) F to increase to counterbalance the rising pressure. Initial depressurization along BCD causes (a) c to remain constant, (b) θ to increase to raise G , and (c) F to diminish. Further decrease in p causes delamination along DP, where (a) contact shrinks, (b) θ to rise further, and (c) F to diminish further. Pinch-off occurs at P when the contact area reduces to a line and the film spontaneously detaches from the plate. Stronger adhesion with $\gamma = 20$ retraces the loading path OAB. Initial depressurization along BCDHK where the contact remains unchanged. Further decrease in p leads to delamination along KQ. Pull-off occurs at Q when $dp/dc = 0$.

remains at 0. The residual stress locked up in the contact area, $\sigma_0(x)$, increases from the center to a maximum with $\sigma_0(x=c) = \sigma$, and is continuous into the freestanding sections. Depressurization at B does not lead to immediate delamination, since $\theta = 0$ implying $G = 0 < \gamma$. Along BCD, θ increases and raises G until the onset of delamination where $G = \gamma$ at D. Further decrease in p along DP shrinks the contact area according to Eq. (4). The mechanical response during delamination, $p(c, w_0)$, for a fixed γ can therefore be determined in a self-consistent manner. At P, the film turns into a cusp making a line contact with the plate. Incremental increase in suction leads to spontaneous *pinch-off* where $c^* = 0$ at the critical pressure p^* . In a strong membrane-plate interface with $\gamma = 20$, depressurization proceeds along BCDHK raising G from zero to $G = \gamma$. Delamination occurs along KQ. At Q, $p^* \approx -\gamma/w_0$ and $dp/dc = 0$, further decrease in p can no longer follow the

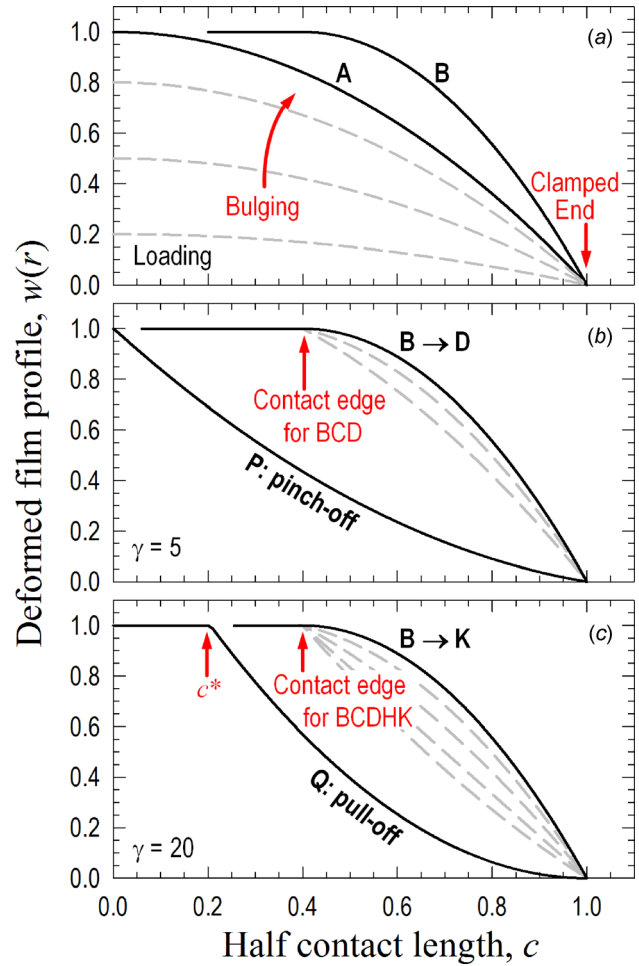


Fig. 3 Changing film profile for $w_0 = 1$. (a) Initial pressurization along OAB causes the film to bulge and the contact to expand. (b) For $\gamma = 5$, pressure decreases along BCDP. Along BCD, the contact area remains unchanged but θ increases. Delamination occurs along DP until pinch-off at P. (c) For $\gamma = 20$, pressure decreases along BCDHKQ with pull-off at Q. The curves are labeled based on Fig. 2.

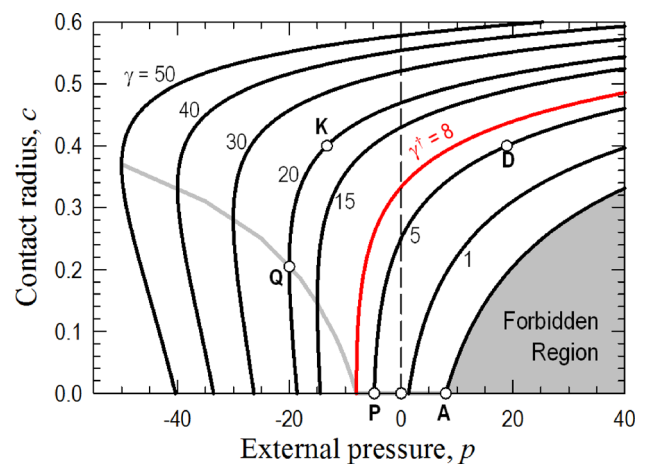


Fig. 4 Contact length as a function of applied pressure for $w_0 = 1$ and a range of adhesion energy. The lowest curve corresponds to $\gamma = 0$, and the area underneath is forbidden. Curves labeled $\gamma = 5$ and $\gamma = 20$ correspond to those shown in Figs. 2 and 3. Curve labeled $\gamma^\dagger = 8$ indicates the transition from pinch-off to pull-off. The locus of pull-off ($dp/dc = 0$) is shown as gray curve.

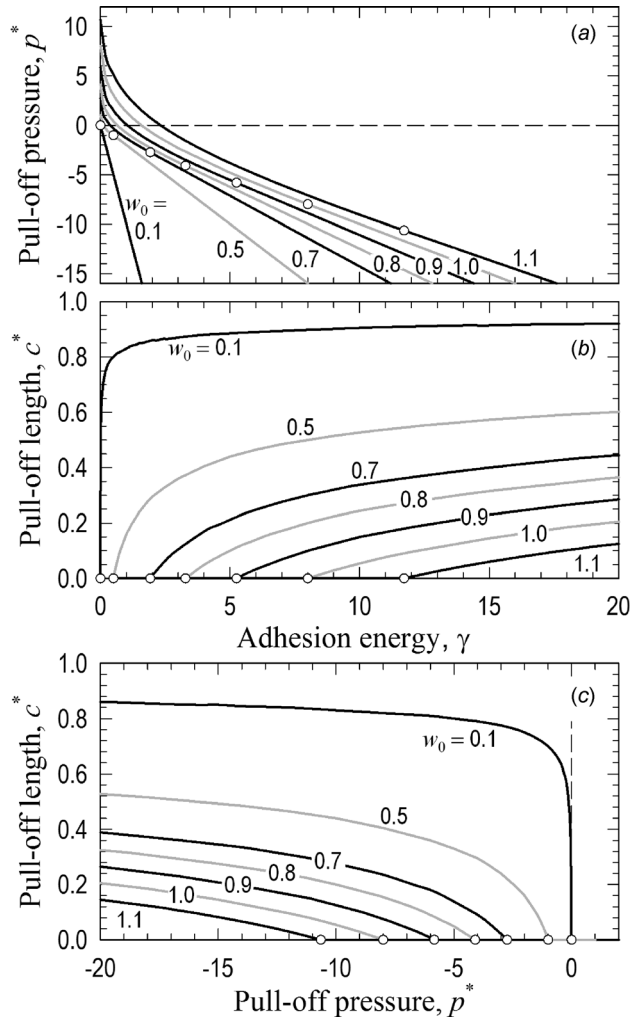


Fig. 5 Relations of “pull-off” parameters for a range of w_0 . (a) Critical pressure and (b) contact length as functions of adhesion energy with a range of gap w_0 . (c) Critical contact length as a function of critical pressure. The symbols denote the transition $\gamma = \gamma^*$ from pinch-off to pull-off.

energy balance and pull-off occurs with $c^* > 0$. Figure 4 shows a family of delamination curves for a range of γ with $w_0 = 1$, and the gray curve shows the pull-off locus, $c^*(p^*)$. Weak interface with $\gamma < \gamma^* = 8$ leads to pinch-off with $c^* = 0$. If w_0 is allowed to span a range, Eq. (4) yields

$$\gamma = 8w_0^4 \times \left\{ \frac{7\Phi^{*2} - 20\Phi^* + 19}{6(\Phi^* - 2)^4} \right\} \quad (5)$$

with $\Phi^* = p^*/F^* \leq 1$. The threshold governing the transition from pinch-off to pull-off is given by $\gamma^* = 8w_0^4$ with $\Phi^* = 1$ and $c^* = 0$

in Eq. (5). It is therefore possible experimentally to choose a specific w_0 to ensure pinch-off rather than pull-off. One interesting outcome from the present model is that if $\gamma_0 = 19w_0^4/12$, pinch-off occurs at $p^* = 0$ corresponding to a tensile force on the constraining plate of $F^* = -3w_0^3$, which is consistent with our earlier work in a 1D punch test in the absence of pressure [3].

Figure 5 shows the interrelation of the pinch-off/pull-off parameters (c^* , p^* , w_0 , γ). It is worthwhile to compare the current 1D results with the two-dimensional (2D) circular film counterpart [1]. Figures 5(a) and 5(b) shows the monotonic decreasing $p^*(\gamma)$ and increasing $c^*(\gamma)$, respectively, which are similar to the 2D counterpart. Figure 5(c) shows that 1D pinch-off is possible as long as $\gamma < \gamma^*$, and pull-off always requires suction ($p^* < 0$). In contrary, 2D allows pinch-off only when $\gamma = 0$ and pull-off for $\gamma > 0$. Note also that $c^*(p^* = 0) = 0$ in 1D, but $c^*(p^* = 0) = 0.2060$ in 2D. The present model is useful in designing microelectromechanical devices as well as devising testing method to measure thin film adhesion.

As a last remark, it is noted that clamping only the two opposite edges of a rectangular film with finite width while applying a uniform pressure is practically challenging. One possible way to realize the configuration is to resort to a three-dimensional axisymmetric setup. A rectangular film wraps around the rims of two thick concentric circular plates of radius, R , separated by a small gap, $2a$, to create a hermetic setup to retain the applied pressure. A rectangular strip is then bent into a circle with diameter $2R + 2w_0$ to serve as the constraining plate. The present model has to be modified to accommodate the three-dimensional geometry and the new boundary conditions, but will nonetheless serves as a limiting case for $R \gg a$ and $R \rightarrow \infty$. Another possible geometry is to have a very wide rectangular film with a narrow freestanding portion, where our solution will be valid at the central region away from the edges.

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